

TSMC-00-240



April 17, 2001

GAU 1743

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9-10-01

Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/769,812 01/26/01

Li-Te Lin, Li-Chih Chao,
Chia-Shiung Tsai

AN ORGANIC LOW K DIELECTRIC ETCH
WITH NH3 CHEMISTRY

Grp. Art Unit: 1743

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INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 6,071,815 to Kleinhenz et al., "Method of
Patterning Sidewalls of a Trench in Integrated Circuit
Manufacturing", discloses a silicon oxide layer etch that uses
HF and ammonia in combination with other gases.



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ASSOCIATE POWER OF ATTORNEY

I hereby appoint William Stoffel, registration number
39,390, as my associate attorney in this case. His telephone
number is (215) 564-2258.

Please continue to direct all correspondence in this case
to the undersigned attorney.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "SBA".

Stephen B. Ackerman,

Principal attorney of record

RECEIVED

APR 23 2001

MAIL ROOM

U.S. Patent 5,897,377 to Suzuki, "Semiconductor Device Manufacturing Method with Use of Gas Including Acyl-Group-Containing Compound", discloses a surface treatment etch.

U.S. Patent 5,972,235 to Brigham et al., "Plasma Etching Using Polycarbonate Mask and Low Pressure-High Density Plasma", discloses a low-k etch.

U.S. Patent 6,063,712 to Gilton et al., "Oxide Etch and Method of Etching", teaches an oxide etch using ammonia a fluorine containing compound and a boron containing compound.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the typed name.

Stephen B. Ackerman,
Reg. No. 37761